AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A probe sheet unit being a sensing section of a semiconductor wafer measuring instrument comprising:

a base plate mountable to a prober of the instrument;

a sheet member mounted to the base plate; and

plural measurement probes provided on one surface of the sheet member, wherein

the plural measurement probes are elastically deformable respectively in response to a force

acting on the top thereof for varying proximity from the top of the probe to said sheet member and

said sheet member is elastically deformable in response to a force acting thereon through the

respective measurement probes for varying proximity therefrom to said base plate,

wherein a proximity to the sheet member is variable in order to absorb and accommodate a plurality of dispersion in heights of electrodes of a measurement objective so as to accommodate inclination and warp of the measurement objective as a whole.

Claim 2 (previously presented): A probe sheet unit according to claim 1, wherein wiring patterns are formed inside and/or on a surface of the sheet member and an external electrode connected electrically to the probes through the wiring patterns is provided on the surface of the sheet member.

Claim 3 (previously presented): A probe sheet unit according to claim 2, wherein circuit elements are provided inside and/or on a surface of the sheet member and the circuit elements are connected electrically to the wiring patterns.

Claim 4 (previously presented): A probe sheet unit according to claim 1, wherein each of the probes is curved and supported at one end thereof and a reinforcing member with an elasticity higher than a probe is provided integrally with the probe on a surface thereof facing the sheet member along the length direction.

Claim 5 (previously presented): A probe sheet unit according to claim 1, wherein each of the probes is curved and a top portion thereof is contactable with said electrodes of the measurement objective, and an reinforcement member with an elasticity higher than the probe is provided on said surface of the sheet member to be located between the sheet member and an opposite side of the probe from the top thereof.

Claim 6 (previously presented): A probe sheet unit according to claim 1, wherein the sheet member is made of a material with a linear expansion coefficient in the range of from 2.5 to 10.5 ppm/°C.

U.S. Patent Application Serial No. 10/709,629 Reply to OA dated October 6, 2005

Claim 7 (previously presented): A probe sheet unit according to claim 1, wherein an elastic member interposed between the base plate and the sheet member.

Claim 8 (Canceled).